

IN THE CLAIMS:

1. (Currently Amended) A bonding apparatus comprising a bonding part which bonds together a plurality of substrates coated with an adhesive agent, and a curing part which cures the adhesive agent of the substrates that have been bonded together, characterized in that

the bonding apparatus has conveying means which conveys the substrates from the bonding part to the curing part, and

the conveying means has a standing part which allows the bonded substrates to stand at room temperature in the atmosphere while conveying the plurality of substrates following bonding.

2. (Original) The bonding apparatus according to claim 1, characterized in that the conveying means is a turntable which rotates while carrying a plurality of substrates.

3. (Original) The bonding apparatus according to claim 2, characterized in that a plurality of the turntables are provided.

4. (Original) The bonding apparatus according to claim 3, characterized in that the plurality of turntables include concentric small-diameter and large-diameter tables.

5. (Original) The bonding apparatus according to claim 3, characterized in that the plurality of turntables include a large-diameter table, and a plurality of small-diameter tables which are disposed on the large-diameter table so that the small-diameter tables can rotate about different axes.

6. (Original) The bonding apparatus according to claim 1, characterized in that the conveying means is an endless or curvilinear conveyor.

7. (Original) The bonding apparatus according to claim 1, characterized in that the conveying means has an accommodating part which stacks and accommodates a plurality of substrates that are conveyed from the bonding part while conveying the substrates to the curing part.

8. (Currently Amended) The bonding apparatus according to ~~any one of claims 1 through 7~~ claim 1, characterized in that the conveying means is formed so that no operation of shifting the substrates is performed in an interval extending from the bonding part to the curing part.

9. (Currently Amended) The bonding apparatus according to ~~any one of claims 1 through 8~~ claim 1, characterized in that the conveying time in the standing part is set to be a time that is at least equal to the time required in order to correct warping of the substrates following bonding.

10. (Currently Amended) A bonding method in which a plurality of substrates are coated with an adhesive agent, the substrates are bonded ~~together~~, and the adhesive agent is cured, characterized in that

the plurality of substrates are allowed to stand at room temperature in the atmosphere at ~~an intermediate point in the conveying process from an~~ while being conveyed from the bonding position for the substrates to ~~[[an]]~~ the curing position for the adhesive agent.

11. (Original) The bonding method according to claim 10, characterized in that the time used for the standing includes at least the time required for correction of the warping of the bonded substrates.

12. (Currently Amended) The bonding method according to claim 10 ~~of claim 11~~, characterized in that the substrates are conveyed without performing any shifting operation in the interval extending from the bonding position for the substrates to the curing position for the adhesive agent.

13. (Currently Amended) The bonding method according to ~~any one of claims 10 through 12~~ claim 10, characterized in that the conveyance is performed by means of a turntable.

14. (Currently Amended) The bonding method according to ~~any one of claims 10 through 12~~ claim 10, characterized in that the conveyance is performed by means of an endless or curvilinear conveyor.